

Vishay Siliconix

# N-Channel 20-V (D-S) MOSFET

PRODU	PRODUCT SUMMARY			
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)	
	$0.420 \text{ at V}_{GS} = 4.5 \text{ V}$	0.606		
20	0.501 at $V_{GS} = 2.5 \text{ V}$	0.505	0.92	
	0.660 at V <sub>GS</sub> = 1.8 V	0.15		

#### **FEATURES**

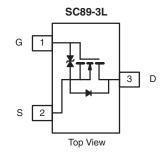
- Halogen-free Option Available
- TrenchFET<sup>®</sup> Power MOSFET: 1.8 V Rated
- ESD Protected: 2000 V

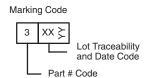


RoHS

#### **APPLICATIONS**

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones, Pagers





Ordering Information: Si1046X-T1-E3 (Lead (Pb)-free)

Si1046X-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	20	V	
Gate-Source Voltage		V <sub>GS</sub>	± 8		
Continuous Proin Current /T = 150 °C\8	T <sub>A</sub> = 25 °C	I_	0.606 <sup>b, c</sup>		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C	I <sub>D</sub>	0.485 <sup>b, c</sup>	А	
Pulsed Drain Current		I <sub>DM</sub>	2.5	^	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	l <sub>S</sub> 0.21 <sup>b, c</sup>			
Marina Daniel District	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.25 <sup>b, c</sup>	W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C	' D	0.16 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Marrian de Ambiento d	t ≤ 5 s	R <sub>thJA</sub>	440	530	°C/W	
Maximum Junction-to-Ambient <sup>b, d</sup>	Steady State	' 'thJA	540	650	C/VV	

#### Notes:

- a. Based on  $T_C = 25$  °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under steady state conditions is 650  $^{\circ}\text{C/W}.$

# Si1046X

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				•			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		20.5		m\//9C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu\text{A}$		- 2.12		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.35		0.95	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 30	mA	
Zava Cata Valtaga Dvain Curvant	I <sub>DSS</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			1	μΑ	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 85 °C			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	2.5			Α	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 0.606 \text{ A}$		0.336	0.420	Ω	
		$V_{GS} = 2.5 \text{ V}, I_D = 0.505 \text{ A}$		0.395	0.501		
		V <sub>GS</sub> = 1.8 V, I <sub>D</sub> = 0.150 A		0.438	0.660		
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.606 A		2.1		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			66		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		17			
Reverse Transfer Capacitance	C <sub>rss</sub>	1		7			
Tabal Oata Obania		$V_{DS} = 10 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 0.606 \text{ A}$		0.99	1.49		
Total Gate Charge	$Q_g$			0.92	1.38	nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 0.606 \text{ A}$		0.15			
Gate-Drain Charge	Q <sub>gd</sub>	1		0.30			
Gate Resistance	R <sub>g</sub>	f = 1 MHz		212		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			17	26		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 10 V, $R_L$ = 20.8 $\Omega$		19	28.5	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 0.48 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		76	114		
Fall Time	t <sub>f</sub>	]		27	41		
<b>Drain-Source Body Diode Characterist</b>	ics			•			
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				2.5	Α	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 0.48 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			16	24	nC	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1 1 0 4 dl/dt 100 4/:		4.8	7.2	ns	
Reverse Recovery Fall Time	t <sub>a</sub>	I <sub>F</sub> = 1.0 A, dl/dt = 100 A/μs		12.3			
Reverse Recovery Rise Time	t <sub>b</sub>	1		3.7			

#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

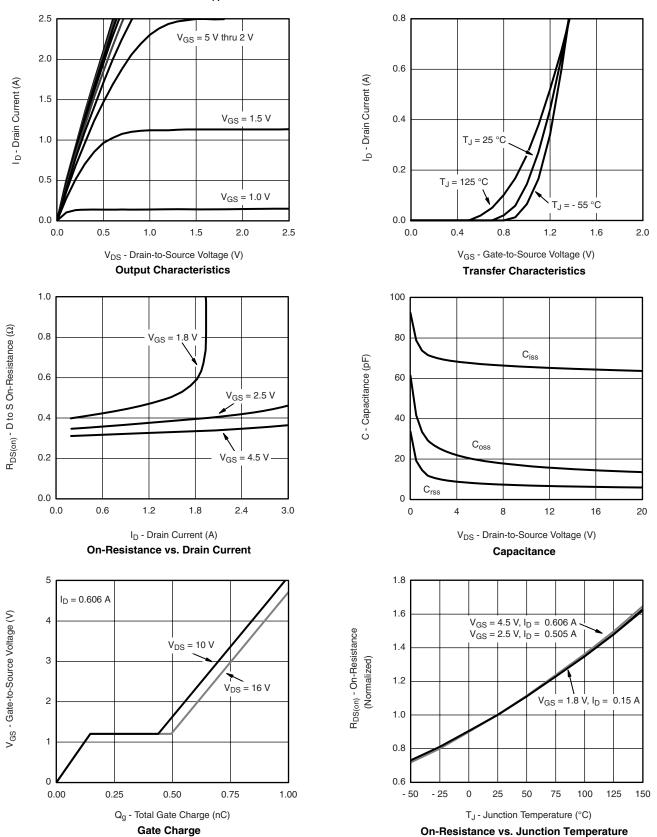
a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.



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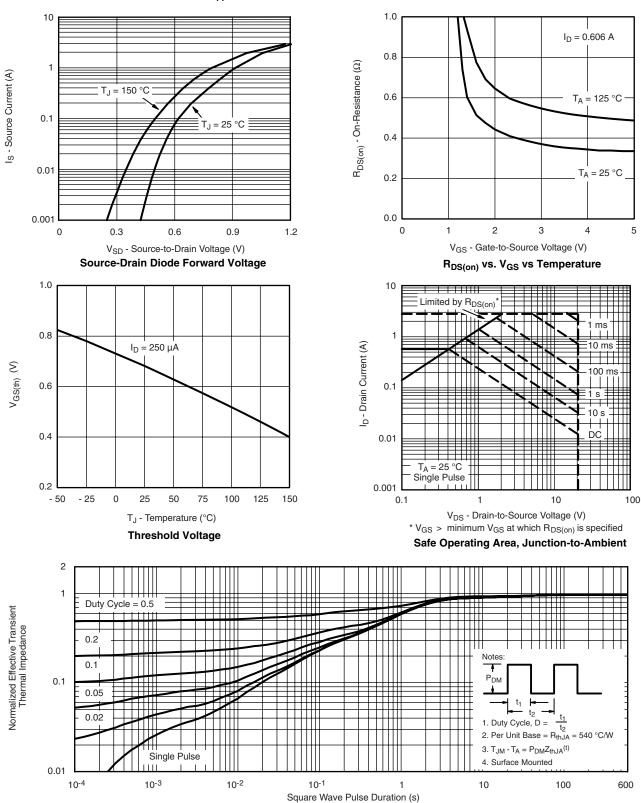
## **TYPICAL CHARACTERISTICS** $T_A = 25$ °C, unless otherwise noted



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Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="http://www.vishay.com/ppg?74594">http://www.vishay.com/ppg?74594</a>.



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